



30th International Conference on Microelectronic Test Structures

March 27-30, 2017, Grenoble, France

Looking for the best opportunity to present and discuss your ideas and results about test structures, measurements and characterization, this is your chance! [Join the 30th ICMTS conference.](#)

A **tutorial Short Course** will precede the conference on March 27, 2017.

Several of the best measurement, equipment, design, and manufacturing experts, will participate to the **equipment exhibition** and presentations.

The conference will bring together designers and users of test structures to discuss recent developments and future directions, in a **one track program**, with convivial breaks allowing attendees to discuss and exchange viewpoints and challenges.

A **Best Paper** award will be presented by the Technical Program Committee.

The conference is **co-sponsored by the IEEE Electron Devices Society** and all published papers, if presented, will be posted to **IEEE Xplore®**.

Original papers are solicited presenting new developments in **topics relevant to ICMTS, including but not limited to, test structures measurements and results, about:**

- R&D and Manufacture of IC, M(N)EMS, Sensors, Actuators, Bio, solar, displays, and emergent technologies.
- Material – Process – New technologies Characterizations.
- New devices – Memory Cells – Arrays.
- DC – Pulsed – RF: measurements techniques and applications.
- Design methods – Verification – Metrology.
- Devices and Circuits Modeling – Parameter Extraction.
- Matching – Variability.
- Reliability – Wafer level / thermal Product Failure Analysis & prediction.
- Yield Enhancement – Production Process Control.
- Measurements – Statistical – Probing – Throughput - Analysis – Strategies.

Author's abstract submission consists in up to four pages in PDF format (font-embedded).

The first page includes a title, a 50-words summary, author name(s), the full address, fax number, and e-mail address of the lead author, and preference for oral or poster session presentation, if any. The body of the abstract should consist of one page of text (800 to 1000 words) and up to two pages containing major figures and tables.

The selection process will be based on the technical merit and will be highly weighted **in favor of papers with high test structure content**, illustration of it and including measured data and analysis.

The submission deadline is extended to October 23, 2016.

Submit your abstract by email to ICMTS2017-Abstract@insight-outside.fr

Notice of **paper acceptance**, will be sent to the selected authors by **early December, 2016**, with instructions for manuscript preparation for the conference proceedings.

The **deadline** for submission of the **final paper** will be **January 15, 2017**.

You may care to join the ICMTS group at www.linkedin.com.

Details of the venue, hotel, registration, etc. will be posted progressively at ICMTS 2017 official web site: <http://icmts2017.insight-outside.fr/>.

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